

P805 Thermal conductivity aluminum base copper clad laminate

Features:

Compliance with ROHS requirements, Not included SVHC of REACH regulation.

The thermal conductivity of FR-4 copper clad laminate is higher than that of common FR-4 clad laminate, effectively increase the service life of electronic products.

Good machinability, Good dimensional stability

Electromagnetic shielding and good cost performance

Application:

LED lighting、LED Stage lighting

Aluminum material: 1060#

Thickness: 0.6~2.0mm

Copper foil : 0.5OZ、1OZ、2OZ

Size: 1000mm*1200mm

Functions:

Item	Experimental method	Unit	Typical Value
Dielectric layer thickness	IPC-TM-650 2.2.18.1	um	80~85
Thermal Stress	IPC-TM-650-2.4.13.1	Min	288℃ > 120s
Peel Strength	IPC-TM-650-2.4.8.1	N/mm	> 1.0
Full voltage resistance	IPC-TM-650-2.5.6	KV(DC)	> 2000
Dielectric Break-down	IPC-TM-650-2.5.6	KV(AC)	> 2000
TG (DSC)	IPC-TM-650-2.4.25	℃	> 135
Thermal expansion coefficient (TMA)	IPC-TM-650-2.4.24	% (50~260℃)	3.2
Surface Resistance	IPC-TM-650-2.5.17.1	MΩ	> 10 ⁴
Volume Resistance	IPC-TM-650-2.5.17.1	MΩ . cm	> 10 ⁶
Permittivity 1MHZ	IPC-TM-650-2.5.5.9	/	/
Dielectric Loss Tangent 1MHZ	IPC-TM-650-2.5.5.9	/	/
Thermal conductivity	ASTM D 5470	W/m.k	> 0.4
R Thermal Resistance	/	℃/W	0.6
Combustibility	Not applicable		



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